

Product/Process Change Notification

N° 2021-029-A

Dear customer,

please find attached our Infineon Technologies AG PCN:

Several changes affecting product TLS805B1SJV

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before 2021-08-18.
- Infineon aligns with the widely-recognized JEDEC STANDARD "JESD46", which stipulates: "Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change."

Notwithstanding the aforesaid individual agreements shall prevail.

Your prompt reply will help Infineon to assure a smooth and well-executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.



On 16 April 2020, Infineon acquired Cypress. We are now in the process of merging and consolidating our tools and processes for PCN, Information Notes, Errata and Product Discontinuance. We ask for your patience in the meantime. For further details, please visit our website: <u>https://www.infineon.com/cms/en/about-infineon/company/cypress-acquisition/</u>

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Product/Process Change Notification

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Products affected	Please refer to attached affected product list 1_cip21029_A				
Detailed change information					
-					
Subject:	Several changes affecting product TLS805B1SJV				
Reason/Motivation:	Expansion of wafer production and wafer test to assure continuity of supply and enable flexible manufacturing. Change of assembly process to harmonize the DSO package platform process.				
Description	<u>Old</u>	New			
PROCESS - WAFER PRODUCTION: Move all or parts of production to a different wafer fab site.		Infineon Technologies Austria AG, Villach, Austria AND Infineon Technologies (Kulim) Sdn. Bhd., Kulim, Malaysia			
PROCESS - ASSEMBLY: Change of lead frame finishing material / area (internal)		Ag spot AND Ag ring			
PROCESS - ASSEMBLY: Die attach material		EN4900 AND AB3230			
TEST FLOW: Move of all or part of electrical wafer test and/or final test to a different test site.	Infineon Technologies Austria AG,	Infineon Technologies Austria AG, Villach, Austria AND Infineon Technologies (Kulim) Sdn. Bhd., Kulim, Malaysia			



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Product identification	Wafer lot numbers from Villach start with VExxxxxx. Wafer lot numbers from Kulim with 1Exxxxxx Traceability assured via date code. No change in SP ordering number		
Anticipated impact of change	Based on the qualification performed, Infineon does not expect any negative impact on quality, function and reliability. No change in fit, form and function expected.		
	DeQuMa-ID(s): SEM-PW-13 / SEM-PA-04 / SEM-PA-07 / SEM-TF-01		
Attachments	1_cip21029_A affected product list		
Time schedule			
Final qualification report	available		
First samples available	on request		
Intended start of delivery [1]	2022-01-14		
Last order date (LOD) [2]	2022-01-14		
Last delivery date (LDD) [3]	2023-01-16		

[3] Delivery of new product can be earlier (see Intended start of delivery) and depends on approval

If you have any questions, please do not hesitate to contact your local sales office.



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Sales name	SP number	OPN	Package
TLS805B1SJV	SP001179580	TLS805B1SJVXUMA1	PG-DSO-8-44
TLS805B1SJV	SP001179580	TLS805B1SJVXUMA1	PG-DSO-8-71